MULTI-INNO TECHNOLOGY CO., LTD.

www.multi-inno.com

OLED MODULE SPECIFICATION

Model : MI12864AO-3

This module uses ROHS material

For Customer's Acceptance:

Customer	
Approved	
Comment	

Revision	1.2
Engineering	
Date	2013-08-14
Our Reference	

REVISION RECORD

REV NO.	REV DATE	CONTENTS	REMARKS
1.0	2009-11-10	Preliminary	
1.1	2012-12-19	Update life time	
1.2	2013-08-14	Update life time Update block diagram Update DC characteristics Update 80XX-series MPU parallel interface timing characteristics Update actual application example	

CONTENT

■ PHYSICAL DATA

No.	Items	Specification	Unit
1	Display Mode	Passive Matrix OLED	-
2	Display Color	Monochrome (White/16 gray scales)	-
3	Duty	1/64	-
4	Resolution	128 (H) x 64 (V)	Pixel
5	Active Area	61.41 (W) x 30.69 (H)	mm
6	Outline Dimension	73.00 (W) x 41.86 (H) x 3.40 (D)	mm
7	Pixel Pitch	0.48 (W) x 0.48 (H)	mm
8	Pixel Size	0.45 (W) x 0.45 (H)	mm
9	Driver IC	SSD1325	-
10	Interface	8-bit parallel,4-wire SPI	-
11	Weight	20.5	g

■ EXTERNAL DIMENSIONS

Notes:
1. Color: White
2. Driver IC: SSD1325
3. TCP Number: SSD1325T2 / SSD1325T6
4. Interface:
   8-bit 68XX/80XX Parallel, 4-wire SPI
5. General Tolerance: ±0.30

Active Area 2.70"
128 x 64 Pixels

Contact Side

MULTI-INNO TECHNOLOGY CO.,LTD.

	CUSTOMER				
CUSTOMER APVL				DATE	
DRAWN		SCALE		TITLE	MI12864AO-3
DFTG CHK		UNIT	mm		
ENGR CHK				MODEL	
APPROVAL				DWG NO	
				PAGE	1/1
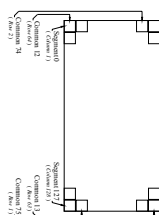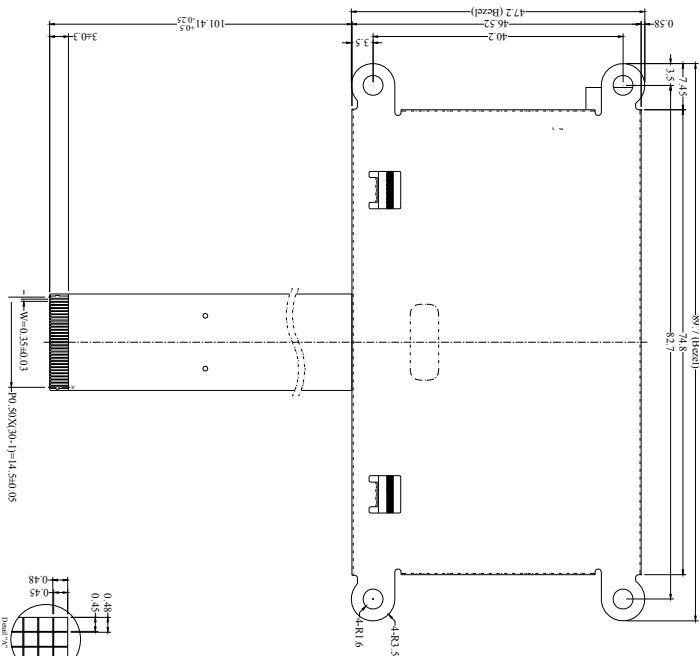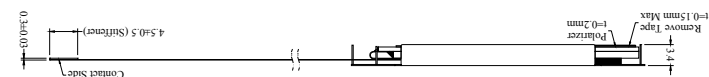
Pin	Symbol
1	N.C.(GND)
2	VCC
3	VCOMH
4	IREF
5	D7
6	D6
7	D5
8	D4
9	D3
10	D2
11	D1
12	D0
13	E/RD#
14	R/W#
15	D/C#
16	RES#
17	CS#
18	N.C.
19	BS2
20	BS1
21	VDD
22	N.C.
23	N.C.
24	N.C.
25	N.C.
26	N.C.
27	N.C.
28	N.C.
29	VSS
30	VSL

■ ABSOLUTE MAXIMUM RATINGS

Items	Symbol	Min	Typ.	Max	Unit	Notes
Supply voltage for logic	V_{DD}	-0.3	-	4	V	1,2
Supply voltage for display	V_{CC}	0	-	16.0	V	1,2
Operating temperature	T_{OP}	-40	-	70	℃	-
Storage temperature	T_{ST}	-40	-	85	℃	-
Life time(80cd/m²)	-	30,000	-	-	hour	3
Life time(60cd/m²)	-	50,000	-	-	hour	3
Life time(40cd/m²)	-	80,000	-	-	hour	3
Humidity	-	-	-	90	%RH	-

Note 1: All the above voltages are on the basis of "$V_{SS} = 0V$".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur.Also,for normal operations,it is desirable to use this module under the conditions according to"electro-optical characteristics".If this module is used beyond these conditions,malfunctioning of the module can occur and the reliability of the module may deteriorate.

Note 3: V_{CC} = 15.0V, T_a = 25°C, 50% Checkerboard.
   Software configuration follows Actual Application Example .
   End of lifetime is specified as 50% of initial brightness reached.The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

■ ELECTRICAL CHARACTERISTICS

◆DC Characteristics

Items	Symbol	Conditions	Min	Typ.	Max	Unit
Supply voltage for logic	V_{DD}		2.4	2.8	3.5	V
Supply voltage for display	V_{CC}	Note 4	14.25	15	15.75	V
High level input	V_{IH}	I_{OUT} = 100μA, 3.3MH	0.8 x V_{DD}	-	V_{DD}	V
Low level input	V_{IL}	I_{OUT} = 100μA, 3.3MH	0	-	0.2 x V_{DD}	V
High level output	V_{OH}	I_{OUT} = 100μA, 3.3MH	0.9 x V_{DD}	-	V_{DD}	V
Low level output	V_{OL}	I_{OUT} = 100μA, 3.3MH	0	-	0.1x V_{DD}	V
Operating current for V_{DD}	I_{DD}		-	250	400	μA
Operating current for V_{CC}	I_{CC}	Note 5	-	22.4	28.0	mA
		Note 6	-	33.7	42.1	mA
		Note 7	-	49.5	61.9	mA
Sleep mode current for V_{DD}	$I_{DD,SLEEP}$		-	1	5	μA
Sleep mode current for V_{CC}	$I_{CC,SLEEP}$		-	1	5	μA

Note 4: Supply Voltage for Display (V_{CC}) are subject to the change of the panel characteristics and the customer's request.

Note 5: V_{DD} = 2.8V, V_{CC} = 15V, 30% Display Area Turn on.

Note 6: V_{DD} = 2.8V, V_{CC} = 15V, 50% Display Area Turn on.

Note 7: V_{DD} = 2.8V, V_{CC} = 15V, 100% Display Area Turn on.

＊Software configuration follows Actual Application Example .

◆AC Characteristics

1. 80XX-Series MPU Parallel Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t_{cycle}	System Cycle Time	300	-	ns
t_{AS}	Address Setup Time	10	-	ns
t_{AH}	Address Hold Time	0	-	ns
t_{DSW}	Write Data Setup Time	40	-	ns
t_{DHW}	Write Data Hold Time	15	-	ns
t_{DHR}	Read Data Hold Time	20	-	ns
t_{OH}	Output Disable Time	-	70	ns
t_{ACC}	Access Time	-	140	ns
t_{PWLR}	Low Pulse Width (Read)	120	-	ns
t_{PWLW}	Low Pulse width (Write)	60		
t_{PWHR}	High Pulse Width (Read)	60	-	ns
t_{PWHW}	High Pulse Width (Write)	60		
t_R	Rise Time	-	15	ns
t_F	Fall Time	-	15	ns
t_{CS}	Chip select setup time	0		Ns
t_{CSH}	Chip select hold time to read signal	0		Ns
t_{CSF}	Chip select hold time	20		ns

* (V_{DD} - V_{SS} = 2.4V to 3.5V, T_a = 25°C)

Write cycle (Form 1) Read cycle (Form 1)

Write cycle (Form 2) Read cycle (Form 2)
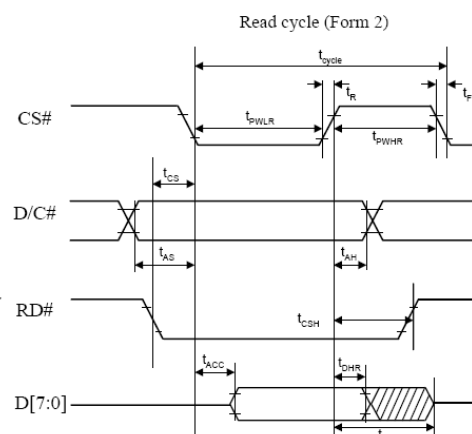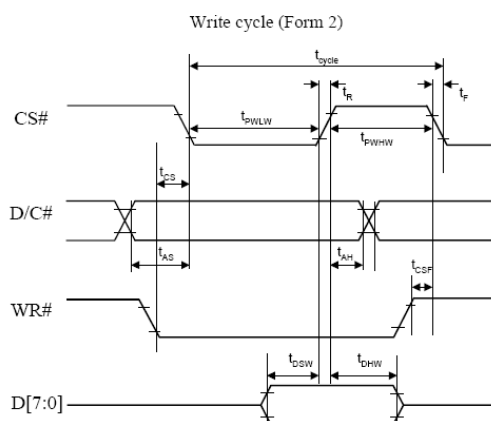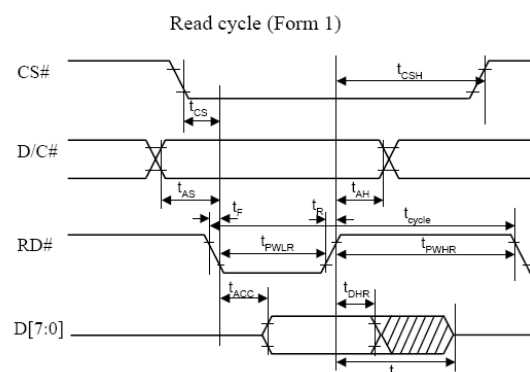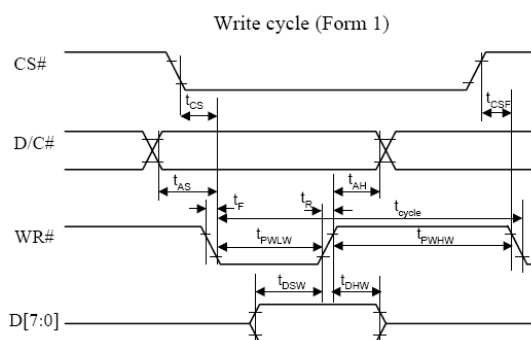
2. 68XX-Series MPU Parallel Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t_{cycle}	System Cycle Time	300	-	ns
t_{AS}	Address Setup Time	0	-	ns
t_{AH}	Address Hold Time	0	-	ns
t_{DSW}	Write Data Setup Time	40	-	ns
t_{DHW}	Write Data Hold Time	15	-	ns
t_{DHR}	Read Data Hold Time	20	-	ns
t_{OH}	Output Disable Time	-	70	ns
t_{ACC}	Access Time	-	140	ns
PW_{CSL}	Chip Select Low Pulse Width (Read)	120	-	ns
	Chip Select Low Pulse width (Write)	60		
PW_{CSH}	Chip Select High Pulse Width (Read)	60		ns
	Chip Select High Pulse Width (Write)	60		
t_R	Rise Time	-	15	ns
t_F	Fall Time	-	15	ns

* ($V_{DD} - V_{SS}$ = 2.4V to 3.5V, T_a = 25°C)
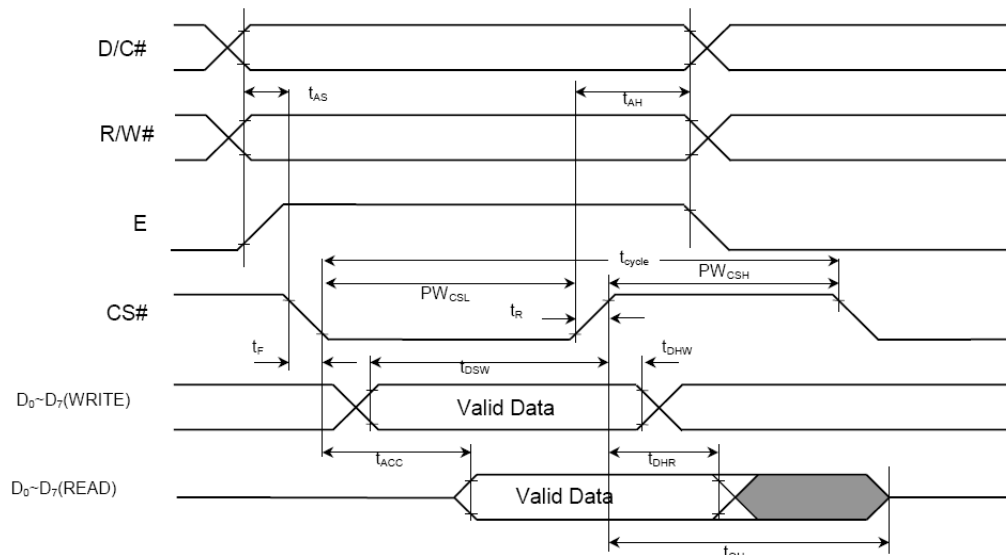
3. Serial Interface Timing Characteristics:

Symbol	Description	Min	Max	Unit
t_{cycle}	Clock Cycle Time	250	-	ns
t_{AS}	Address Setup Time	150	-	ns
t_{AH}	Address Hold Time	150	-	ns
t_{CSS}	Chip Select Setup Time	120	-	ns
t_{CSH}	Chip Select Hold Time	60	-	ns
t_{DSW}	Write Data Setup Time	100	-	ns
t_{DHW}	Write Data Hold Time	100	-	ns
t_{CLKL}	Serial Clock Low Time	100	-	ns
t_{CLKH}	Serial Clock High Time	100	-	ns
t_R	Rise Time	-	15	ns
t_F	Fall Time	-	15	ns

* $(V_{DD} - V_{SS} = 2.4V$ to $3.5V$, $T_a = 25°C)$
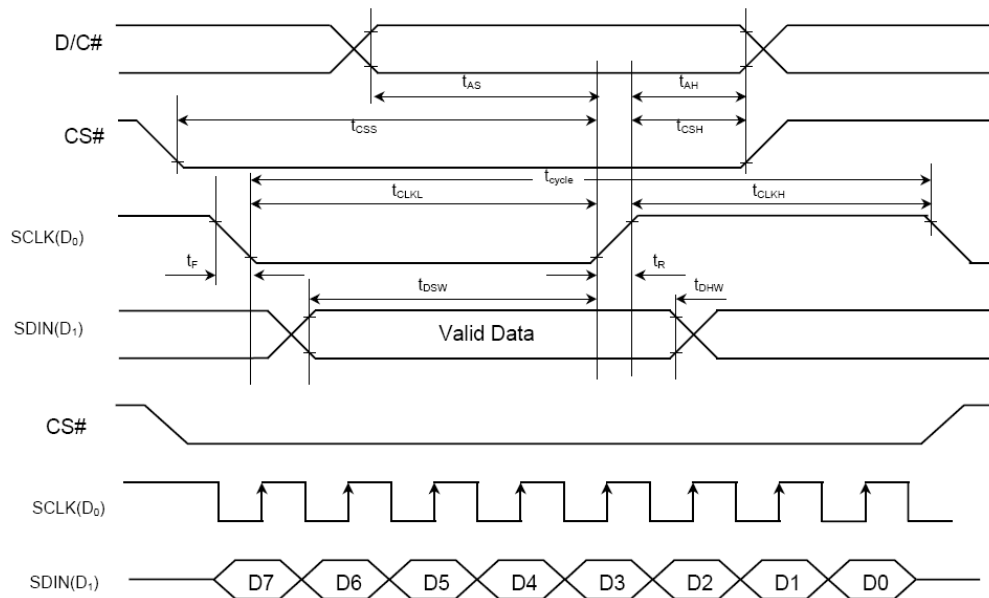
# ■ TIMING OF POWER SUPPLY

1. Commands

Refer to the Technical Manual for the SSD1325

2. Power down and Power up Sequence

To protect OEL panel and extend the panel life time, the driver IC power up/down routine should include a delay period between high voltage and low voltage power sources during turn on/off.   It gives the OEL panel enough time to complete the action of charge and discharge before/after the operation.
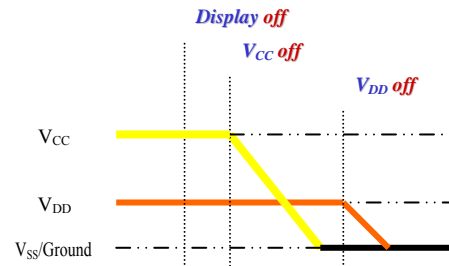
4.2.1 Power up Sequence:

1. Power up V_{DD}
2. Send Display off command
3. Initialization
4. Clear Screen
5. Power up V
6. Delay 100ms
    (When V_{CC} is stable)
7. Send Display on command
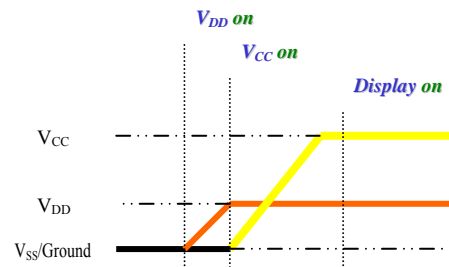
4.2.2 Power down Sequence:

1. Send Display off command
2. Power down V_{CC}
3. Delay 100ms
    (When V_{CC} is reach 0 and panel is completely discharges)
4. Power down V_{DD}

3. Reset Circuit

When RES# input is low, the chip is initialized with the following status:
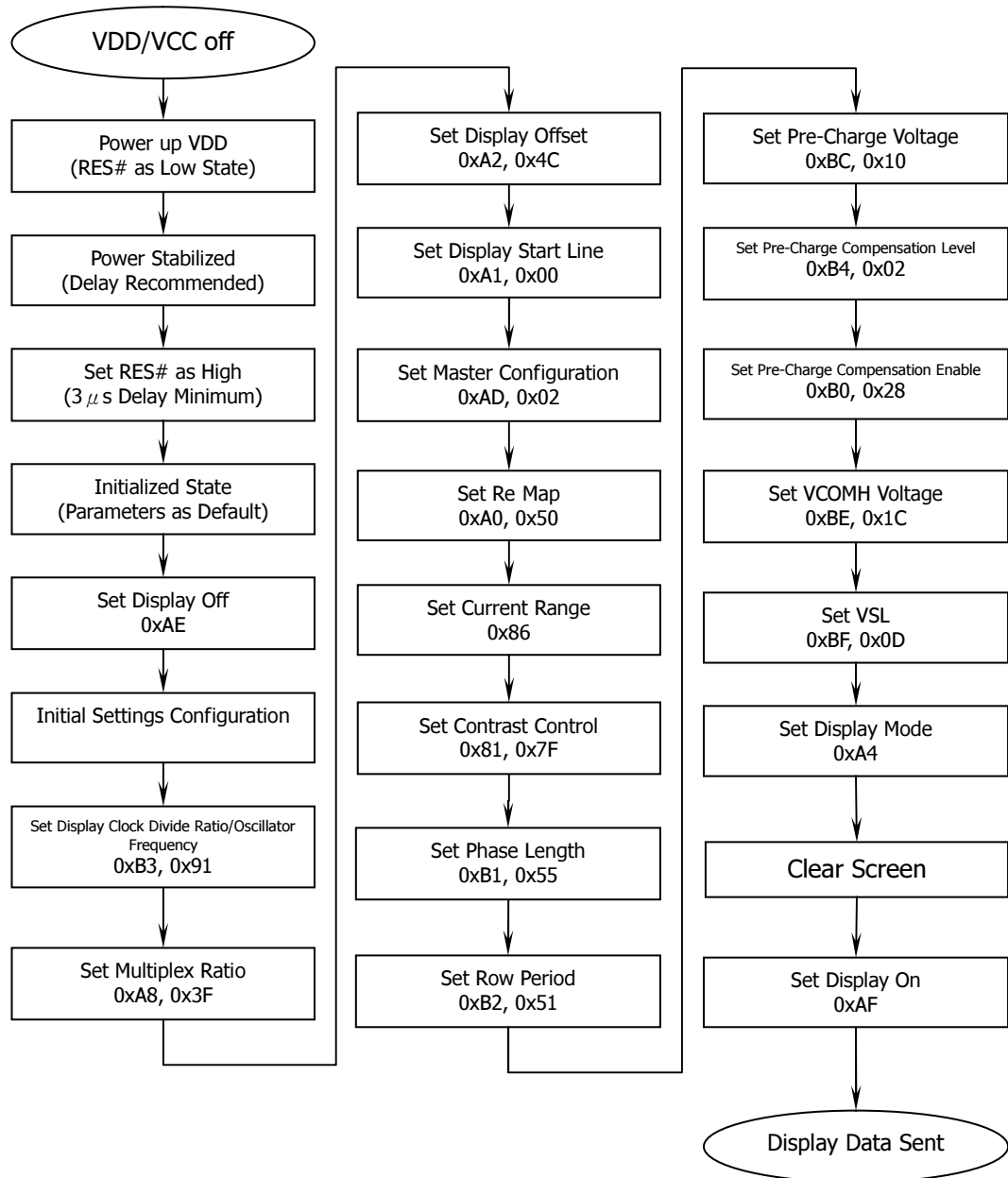1. Display is OFF
2. 128×80 Display Mode
3. Normal segment and display data column and row address mapping (SEG0 mapped to column address 00h and COM0 mapped to row address 00h)
4. Shift register data clear in serial interface
5. Display start line is set at display RAM address 0
6. Column address counter is set at 0
7. Normal scan direction of the COM outputs
8. Contrast control register is set at 80h
9. Normal display mode (Equivalent to A4h command)

4. Actual Application Example

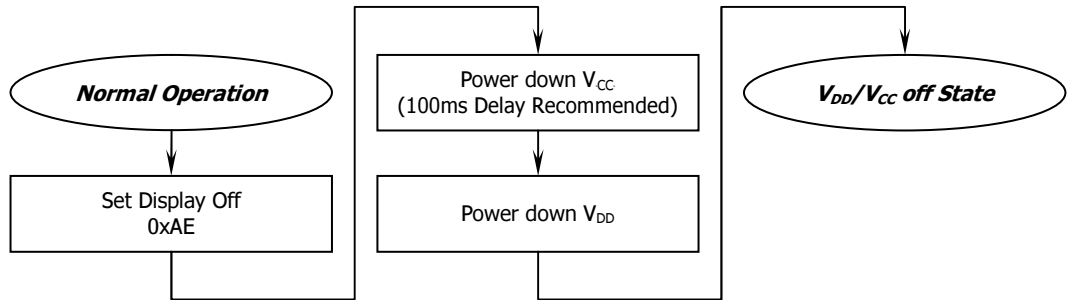Command usage and explanation of an actual example

4.1 V$_{CC}$ Supplied Externally

<Power up Sequence>

```
VDD/VCC off

Power up VDD
(RES# as Low State)

Power Stabilized
(Delay Recommended)

Set RES# as High
(3 μs Delay Minimum)

Initialized State
(Parameters as Default)

Set Display Off
0xAE

Initial Settings Configuration

Set Display Clock Divide Ratio/Oscillator
Frequency
0xB3, 0x91

Set Multiplex Ratio
0xA8, 0x3F
```

```
Set Display Offset
0xA2, 0x4C

Set Display Start Line
0xA1, 0x00

Set Master Configuration
0xAD, 0x02

Set Re Map
0xA0, 0x50

Set Current Range
0x86

Set Contrast Control
0x81, 0x7F

Set Phase Length
0xB1, 0x55

Set Row Period
0xB2, 0x51
```

```
Set Pre-Charge Voltage
0xBC, 0x10

Set Pre-Charge Compensation Level
0xB4, 0x02

Set Pre-Charge Compensation Enable
0xB0, 0x28

Set VCOMH Voltage
0xBE, 0x1C

Set VSL
0xBF, 0x0D

Set Display Mode
0xA4

Clear Screen

Set Display On
0xAF

Display Data Sent
```
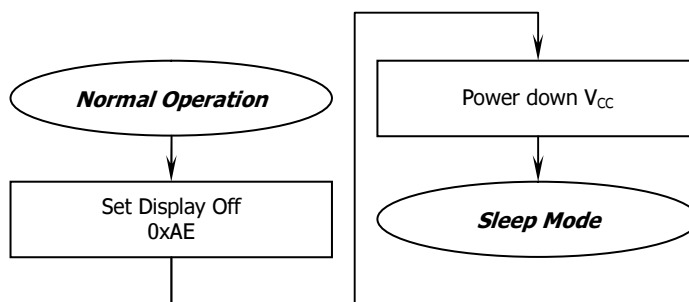
If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.
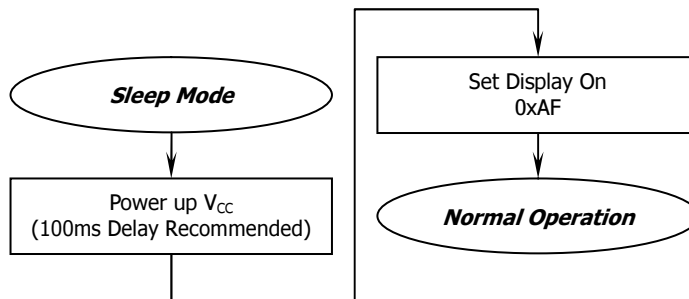
<Power down Sequence>

Normal Operation → Set Display Off 0xAE → Power down V_{CC} (100ms Delay Recommended) → Power down V_{DD} → V_{DD}/V_{CC} off State

<Entering Sleep Mode>

Normal Operation → Set Display Off 0xAE → Power down V_{CC} → Sleep Mode

<Exiting Sleep Mode>

Sleep Mode → Power up V_{CC} (100ms Delay Recommended) → Set Display On 0xAF → Normal Operation

■ ELECTRO-OPTICAL CHARACTERISTICS (Ta=25℃)

Items		Symbol	Min.	Typ.	Max.	Unit	Remark
Operating Luminance		L	-	60	80	cd /m^2	White
Color Coordinate	White\	CIE x	0.25	0.29	0.33	CIE1931	Darkroom
		CIE y	0.27	0.31	0.35		
Response Time	Rise	Tr	-	-	-	ms	-
	Decay	Td	-	-	-	ms	-
Contrast Ratio*		Cr	10000 :1	-	-		Darkroom
Viewing Angle Uniformity		△ θ	-	Free	-	Degree	-

Note : Brightness (L_{br}) is subject to the change of the panel characteristics and the customer's request.

＊Optical measurement taken at V_{DD}= 2.8V, V_{CC}= 12.5V.

Software configuration follows Actual Application Example .

■ INTERFACE PIN CONNECTIONS

1. Block Diagram

C1, C3	:	0.1μF
C2, C6	:	4.7μF
C4	:	10μF
C5	:	4.7μF/25V, Tantalum Capacitor
R1	:	820kΩ, R1 = (Voltage at IREF - VSS) / IREF
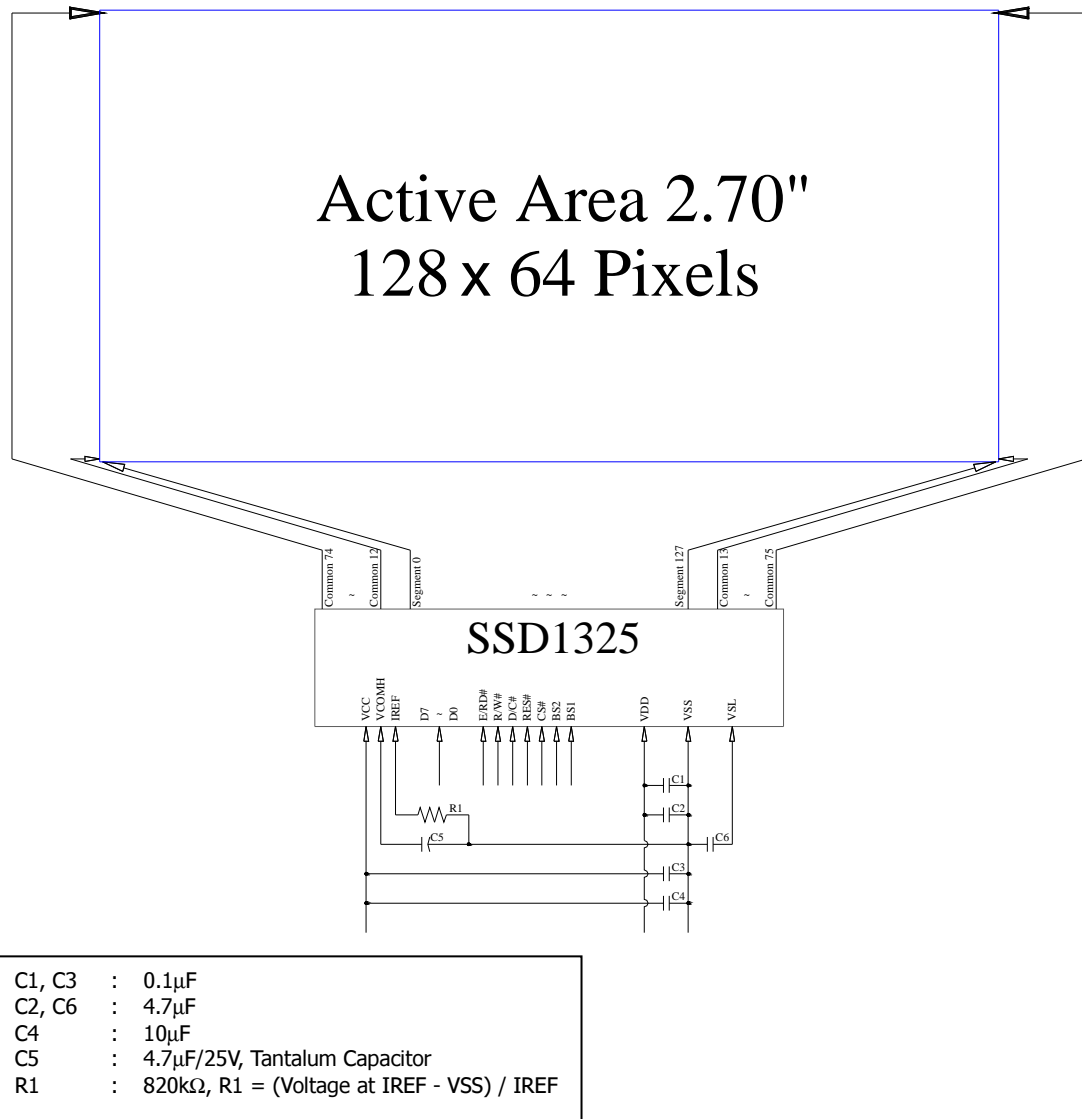
MCU Interface Selection   :   Base on BS1 and BS2 connection
Pins connected to MCU interface   :   D7~D0, E/RD#, R/W#, D/C#, RES#, and CS#
                                            Showed as below table

BS2	BS1	Interface mode	Data bus								Control bus				
			D7	D6	D5	D4	D3	D2	D1	D0	CS#	D/C#	R/W#	E/RD#	RES#
0	0	Serial	**0**	**0**	**0**	**0**	**0**	**NC**	SDIN	SCLK	CS#	D/C#	**0**	**0**	RES#
1	0	8bit 6800	D7	D6	D5	D4	D3	D2	D1	D0	CS#	D/C#	R/W#	E	RES#
1	1	8bit 8080	D7	D6	D5	D4	D3	D2	D1	D0	CS#	D/C#	WR#	RD#	RES#

Note :
     a. ″0″ is connected to VSS.
     b. ″1″ is connected to VDD.
     c. ″NC″ is non-connected.

2. Pin Definition

Pin Number	Symbol	I/O	Function
Power Supply			
21	VDD	P	*Power Supply for Logic Circuit* This is a voltage supply pin. It must be connected to external source.
29	VSS	P	*Ground of OEL System* This is a ground pin. It also acts as a reference for the logic pins, the OEL driving voltages, and the analog circuits. It must be connected to external ground.
2	VCC	P	*Power Supply for OEL Panel* This is the most positive voltage supply pin of the chip. It must be supplied externally.
Driver			
4	IREF	I	*Current Reference for Brightness Adjustment* This pin is segment current reference pin. A resistor should be connected between this pin and VSS. Set the current at 10μA.
3	VCOMH	P	*Voltage Output High Level for COM Signal* This pin is the input pin for the voltage output high level for COM signals. It can be supplied externally o internally. When VCOMH is generated internally, capacitor should be connected between this pin and VSS.
30	VSL	O	*Voltage Output Low Level for SEG Signal* This pin is the output pin for the voltage output low level for SEG signals. A capacitor should be connected between this pin and VSS.
Interface			
20 19	BS1 BS2	I	*Communicating Protocol Select* These pins are MCU interface selection input. See the following table: |	68XX-parallel	80XX-parallel	Serial | |---|---|---|---| | BS1 | 0 | 1 | 0 | | BS2 | 1 | 1 | 0 |
16	RES#	I	*Power Reset for Controller and Driver* This pin is reset signal input. When the pin is low, initialization of the chip is executed.
17	CS#	I	*Chip Select* This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low.
15	D/C#	I	*Data/Command Control* This pin is Data/Command control pin. When the pin is pulled high, the input at D7~D0 is treated as display data. When the pin is pulled low, the input at D7~D0 will be transferred to the command register. For detail relationship to MCU interface signals, please refer to the Timing Characteristics Diagrams. When the pin is pulled high and serial interface mode is selected, the data at SDIN is treated as data. When it is pulled low, the data at SDIN will be transferred to the command register.

Pin Number	Symbol	I/O	Function
Interface(Continued)			
13	E/RD#	I	*Read/Write Enable or Read* This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled high and the CS# is pulled low. When connecting to an 80XX-microprocessor, this pin receives the Read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low.
14	R/W#	I	*Read/Write Select or Write* This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Pull this pin to "High" for read mode and pull it to "Low" for write mode. When 80XX interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled low and the CS# is pulled low.
5~12	D7~D0	I/O	*Host Data Input/Output Bus* These pins are 8-bit bi-directional data bus to be r's data bus. When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK.
Reserve			
18, 22~28	N.C.	-	*Reserved Pin* The N.C. pins between function pins are reserved for compatible and flexible design.
1	N.C. (GND)	-	*Reserved Pin (Supporting Pin)* The supporting pin can reduce the influences from stresses on the function pins. This pin must be connected to external ground.

■ RELIABILITY TESTS

Item		Condition	Criterion
High Temperature Storage (HTS)		80±2℃, 240 hours	1. After testing, the function test is ok. 2. After testing, no addition to the defect. 3. After testing, the change of luminance should be within +/- 50% of initial value. 4. After testing, the change for the mono and area color must be within (+/-0.02, +/-0.02) and for the full color it must be within (+/-0.04, +/-0.04) of initial value based on 1931 CIE coordinates. 5. After testing, the change of total current consumption should be within +/- 50% of initial value.
High Temperature Operating (HTO)		70±2℃, 240 hours	
Low Temperature Storage (LTS)		-40±2℃, 240 hours	
Low Temperature Operating (LTO)		-30±2℃, 240 hours	
High Temperature / High Humidity Storage (HTHHS)		60±3℃, 90%±3%RH, 240 hours	
Thermal Shock (Non-operation) (TS)		-40±2℃ ~ 25℃ ~ 85±2℃ (30min) (5min) (30min) 24cycles	
Vibration (Packing)	10~55~10Hz,amplitude 1.5mm, 1 hour for each direction x, y, z	1. One box for each test. 2. No addition to the cosmetic and the electrical defects.	
Drop (Packing)	Height : 1 m, each time for 6 sides, 3 edges, 1 angle		

Note：1) For each reliability test, the sample quantity is 3, and only for one test item.
   2) The HTHHS test is requested the Pure Water(Resistance＞10MΩ).

■OUTGOING QUALITY CONTROL SPECIFICATION

◆Standard

According to GB/T2828.1-2003/ISO 2859-1：1999 and ANSI/ASQC Z1.4-1993, General Inspection Level II.

◆Definition

1 Major defect : The defect that greatly affect the usability of product.

2 Minor defect : The other defects, such as cosmetic defects, etc.

3 Definition of inspection zone:
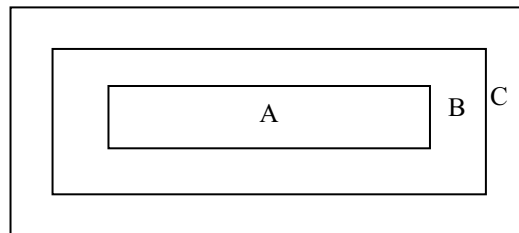
Zone A: Active Area

Zone B: Viewing Area except Zone A

Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of

quality and assembly to customer`s product.

◆Inspection Methods

1 The general inspection : under 20W x 2 or 40W fluorescent light, about 30cm viewing distance, within 45º viewing angle, under 25±5℃.
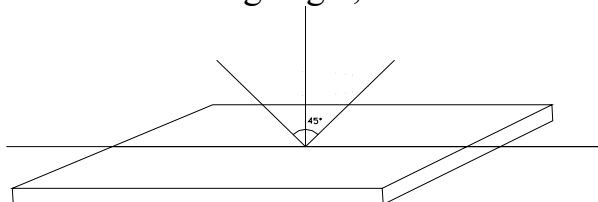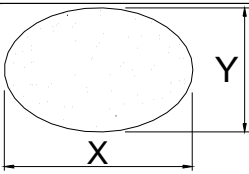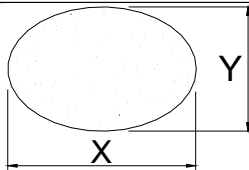

2 The luminance and color coordinate inspection : By PR705 or BM-7 or the equal equipments, in the dark room, under 25±5℃.

◆Inspection Criteria

1 Major defect : AQL= 0.65

Item	Criterion
Function Defect	1. No display or abnormal display is not accepted
	2. Open or short is not accepted.
	3. Power consumption exceeding the spec is not accepted.
Outline Dimension	Outline dimension exceeding the spec is not accepted.
Glass Crack	Glass crack tends to enlarge is not accepted.

2 Minor Defect : AQL= 1.5

Item	Criterion			
Spot Defect (dimming and lighting spot)	Size (mm)		Accepted Qty	
			Area A + Area B	Area C
		$\Phi \leqq 0.10$	Ignored	
		$0.10 < \Phi \leqq 0.15$	3	Ignored
		$0.15 < \Phi \leqq 0.20$	1	
		$0.20 < \Phi$	0	
	Note : $\Phi = (x + y) / 2$			
Line Defect (dimming and lighting line)	L (Length) : mm	W (Width) : mm	Area A + Area B	Area C
	/	$W \leqq 0.03$	Ignored	
	$L \leqq 3.0$	$0.03 < W \leqq 0.05$	2	Ignored
	$L \leqq 2.0$	$0.05 < W \leqq 0.08$	1	
	/	$0.08 < W$	As spot defect	

Remarks: The total of spot defect and line defect shall not exceed 4 pcs.

Item	Criterion			
Polarizer Stain	Stain which can be wiped off lightly with a soft cloth or similar cleaning is accepted, otherwise, according to the Spot Defect and the Line Defect.			
Polarizer Scratch	1. If scratch can be seen during operation, according to the criterions of the Spot Defect and the Line Defect.			
	2. If scratch can be seen only under non-operation or some special angle, the criterion is as below :			
	L (Length) : mm	W (Width) : mm	Area A + Area B	Area C
	/	$W \leqq 0.03$	Ignore	
	$5.0 < L \leqq 10.0$	$0.03 < W \leqq 0.05$	2	Ignore
	$L \leqq 5.0$	$0.05 < W \leqq 0.08$	1	
	/	$0.08 < W$	0	
Polarizer Air Bubble	Size		Area A + Area B	Area C
		$\Phi \leqq 0.20$	Ignored	
		$0.20 < \Phi \leqq 0.50$	2	Ignored
		$0.50 < \Phi \leqq 0.80$	1	
		$0.80 < \Phi$	0	

Glass Defect (Glass Chiped)	1. On the corner		
		(mm)	
		x	≤ 2.0
		y	$\leq S$
		z	$\leq t$
	2. On the bonding edge		
		(mm)	
		x	$\leq a / 2$
		y	$\leq s / 3$
		z	$\leq t$
	3. On the other edges		
		(mm)	
		x	$\leq a / 5$
		y	≤ 1.0
		z	$\leq t$
	Note: t: glass thickness ; s: pad width ; a: the length of the edge		
TCP Defect	Crack, deep fold and deep pressure mark on the TCP are not accepted		
Pixel Size	The tolerance of display pixel dimension should be within ±20% of the spec		
Luminance	Refer to the spec or the reference sample		
Color	Refer to the spec or the reference sample		

■ CAUTIONS IN USING OLED MODULE

◆ Precautions For Handling OLED Module:

1. OLED module consists of glass and polarizer. Pay attention to the following items when handling:

    i. Avoid drop from high, avoid excessive impact and pressure.

    ii. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead.

    iii. If the surface becomes dirty, breathe on the surface and gently wipe it off with a soft dry cloth. If it is terrible dirty, moisten the soft cloth with Isopropyl alcohol or Ethyl alcohol. Other solvents may damage the polarizer. Especially water, Ketone and Aromatic solvents.

    iv. Wipe off saliva or water drops immediately, contact the polarizer with water over a long period of time may cause deformation.

    v. Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peeling-off may occur with high temperature and high humidity.

    vi. Condensation on the surface and the terminals due to cold or anything will damage, stain or dirty the polarizer, so make it clean as the way of iii.

2. Do not attempt to disassemble or process the OLED Module.

3. Make sure the TCP or the FPC of the Module is free of twisting, warping and distortion, do not pull or bend them forcefully, especially the soldering pins. On the other side, the SLIT part of the TCP is made to bend in the necessary case.

4. When assembling the module into other equipment, give the glass enough space to avoid excessive pressure on the glass, especially the glass cover which is much more fragile.

5. Be sure to keep the air pressure under 120 kPa, otherwise the glass cover is to be cracked.

6. Be careful to prevent damage by static electricity:

    i. Be sure to ground the body when handling the OLED Modules.

    ii. All machines and tools required for assembling, such as soldering irons, must be properly grounded.

    iii. Do not assemble and do no other work under dry conditions to reduce the amount of static electricity generated. A relative humidity of 50%-60% is recommended.

    iv. Peel off the protective film slowly to avoid the amount of static electricity generated.

    v. Avoid to touch the circuit, the soldering pins and the IC on the Module by the body.

    vi. Be sure to use anti-static package.

7. Contamination on terminals can cause an electrochemical reaction and corrade the terminal circuit, so make it clean anytime.

8. All terminals should be open, do not attach any conductor or semiconductor on the terminals.

9. When the logic circuit power is off, do not apply the input signals.

10. Power on sequence: $V_{DD} \rightarrow V_{PP}$, and power off sequence: $V_{PP} \rightarrow V_{DD}$.

11. Be sure to keep temperature, humidity and voltage within the ranges of the spec, otherwise shorten Module's life time, even make it damaged.

12. Be sure to drive the OLED Module following the Specification and Datasheet of IC controller, otherwise something wrong may be seen.

13. When displaying images, keep them rolling, and avoid one fixed image displaying more than 30 seconds, otherwise the residue image is to be seen. This is the speciality of OLED.

◆ Precautions For Soldering OLED Module:

1. Soldering temperature : 260°C ± 10°C.
2. Soldering time : 3-4 sec.
3. Repeating time : no more than 3 times.
4. If soldering flux is used, be sure to remove any remaining flux after finishing soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended to protect the surface with a cover during soldering to prevent any damage due to flux spatters.

◆ Precautions For Storing OLED Module:

1. Be sure to store the OLED Module in the vacuum bag with dessicant.
2. If the Module can not be used up in 1 month after the bag being opened, make sure to seal the Module in the vacuum bag with dessicant again.
3. Store the Module in a dark place, do not expose to sunlight or fluorescent light.
4. The polarizer surface should not touch any other objects. It is recommended to store the Module in the shipping container.
5. It is recommended to keep the temperature between 0°C and 30°C , the relative humidity not over 60%.

◆ Limited Warranty

Unless relevant quality agreements signed with customer and law enforcement, for a period of 12 months from date of production, all products (except automotive products) Multi-Inno will replace or repair any of its OLED modules which are found to be functional defect when inspected in accordance with Multi-Inno OLED acceptance standards (copies available upon request). Cosmetic/visual defects must be returned to Multi-Inno within 90 days of shipment. Confirmation of such date should be based on freight documents. The warranty liability of Multi-Inno is limited to repair and/or replacement on the terms above. Multi-Inno will not be responsible for any subsequent or consequential events.

◆ Return OLED Module Under Warranty:

1. No warranty in the case that the precautions are disregarded.
2. Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects.